

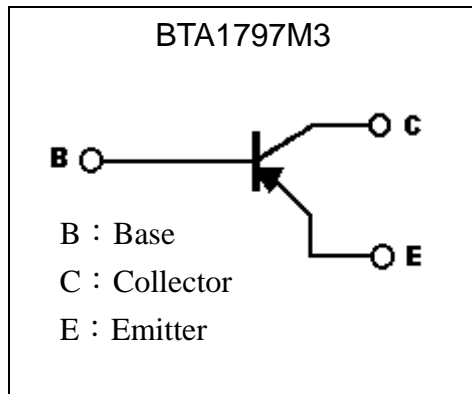
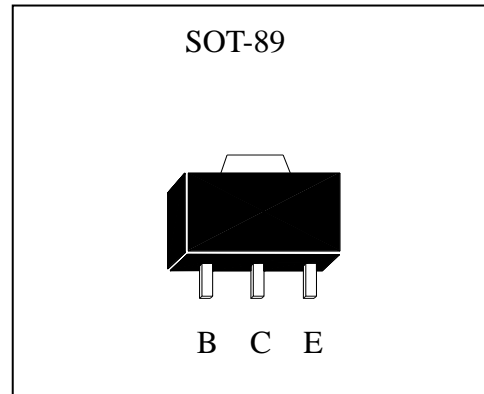
Silicon PNP Epitaxial Planar Transistor

BTA1797M3

BV_{CEO}	-50V
I_C	-3A
$V_{CESAT(Max)}$	-0.2V

Description

- Low saturation voltage, $V_{CE(SAT)} = -0.2V(max.)$ at $I_C/I_B = -1A/-50mA$.
- High current capability.
- Excellent DC current gain characteristics.
- Pb-free lead plating and halogen-free package.

Symbol

Outline

Absolute Maximum Ratings ($T_a = 25^\circ C$)

Parameter	Symbol	Limits	Unit
Collector-Base Voltage	V_{CBO}	-50	V
Collector-Emitter Voltage	V_{CEO}	-50	V
Emitter-Base Voltage	V_{EBO}	-7	V
Collector Current (DC)	I_C	-3	A
Collector Current (Pulse)	I_{CP}	-5 (Note 1)	A
Base Current (DC)	I_B	-0.2	A
Power Dissipation	P_D	0.5	W
		1 (Note 2)	W
		2 (Note 3)	W
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	250	$^\circ C/W$
		125 (Note 2)	$^\circ C/W$
		62.5 (Note 3)	$^\circ C/W$
Operating Junction Temperature Range	T_j	-55~+150	$^\circ C$
Storage Temperature Range	T_{stg}	-55~+150	$^\circ C$

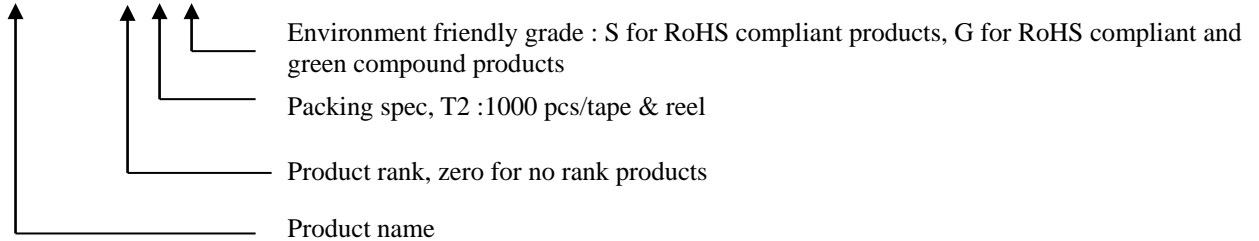
Note : 1. Single Pulse $P_w \leq 300\mu s$, Duty $\leq 2\%$.

2. When mounted on FR-4 PCB with area measuring $10 \times 10 \times 1$ mm.

3. When mounted on ceramic with area measuring $40 \times 40 \times 1$ mm

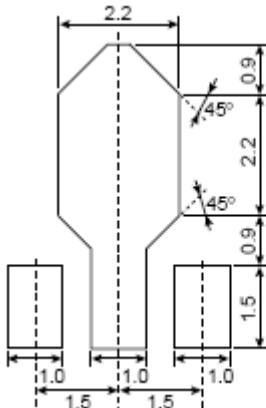
Ordering Information

Device	Package	Shipping
BTA1797M3-0-T2-G	SOT-89 (Pb-free lead plating and halogen-free package)	1000 pcs / Tape & Reel


Characteristics (Ta=25°C)

Symbol	Min.	Typ.	Max.	Unit	Test Conditions
BV_{CBO}	-50	-	-	V	$I_C = -50\mu A, I_E = 0$
BV_{CEO}	-50	-	-	V	$I_C = -1mA, I_B = 0$
BV_{EBO}	-7	-	-	V	$I_E = -50\mu A, I_C = 0$
I_{CBO}	-	-	-100	nA	$V_{CB} = -50V, I_E = 0$
I_{EBO}	-	-	-100	nA	$V_{EB} = -7V, I_C = 0$
* $V_{CE(sat)}$	-	-0.1	-0.2	V	$I_C = -1A, I_B = -50mA$
* $V_{CE(sat)}$	-	-0.19	-0.5	V	$I_C = -2A, I_B = -100mA$
* $V_{BE(sat)}$	-	-0.85	-1.2	V	$I_C = -1A, I_B = -50mA$
* $V_{BE(on)}$	-	-0.78	-1	V	$V_{CE} = -2V, I_C = -1A$
h_{FE1}	180	-	-	-	$V_{CE} = -2V, I_C = -20mA$
h_{FE2}	200	-	400	-	$V_{CE} = -2V, I_C = -500mA$
h_{FE3}	120	-	-	-	$V_{CE} = -2V, I_C = -1A$
f_T	-	180	-	MHz	$V_{CE} = -2V, I_C = -300mA$
Cob	-	24	-	pF	$V_{CB} = -10V, I_E = 0, f = 1MHz$

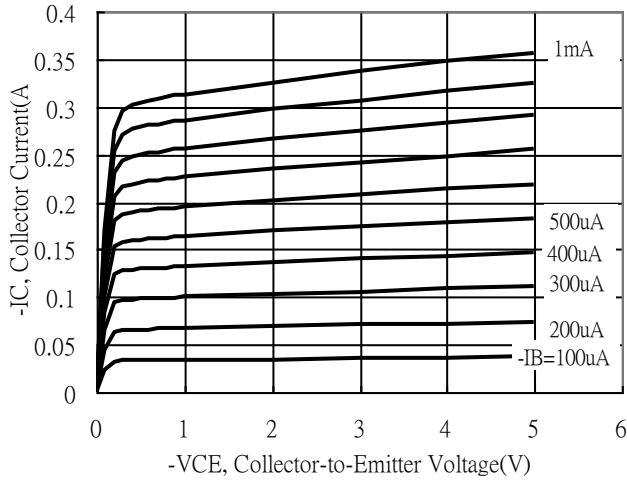
*Pulse Test: Pulse Width $\leq 380\mu s$, Duty Cycle $\leq 2\%$

Recommended soldering footprint


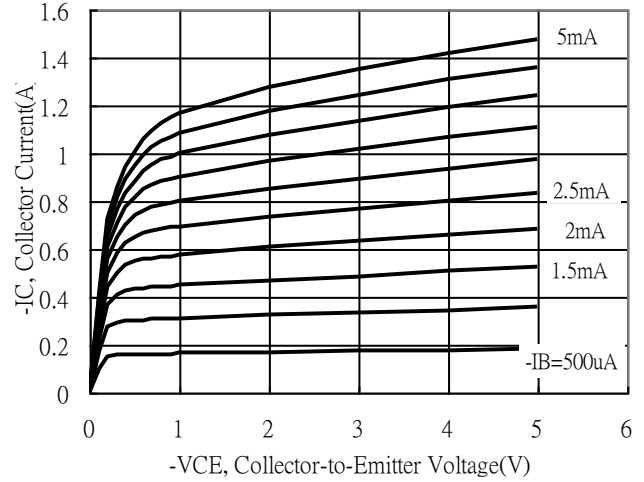
unit : mm

Typical Characteristics

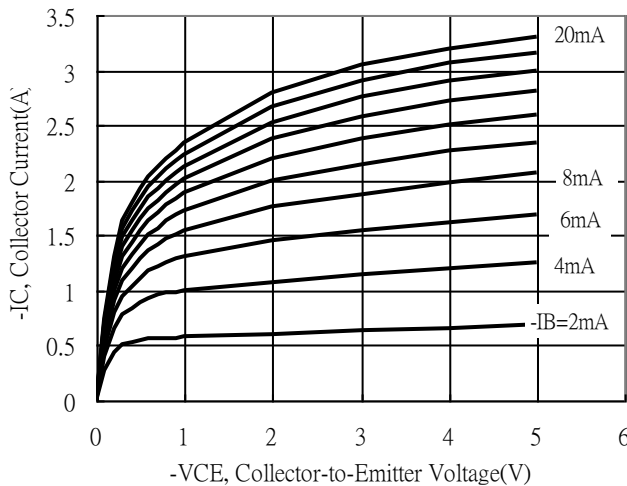
Emitter Grounded Output Characteristics



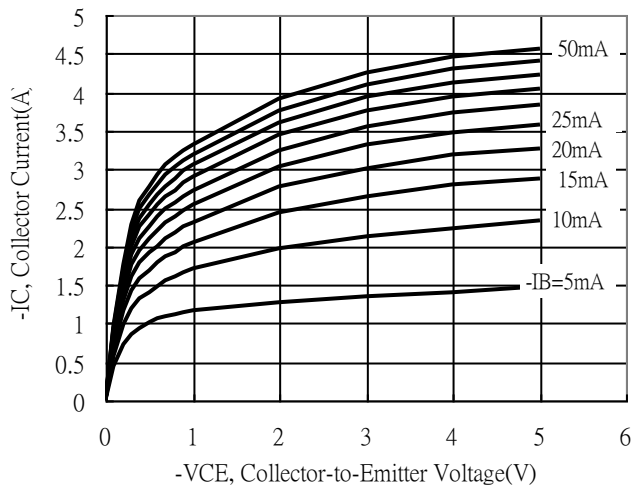
Emitter Grounded Output Characteristics



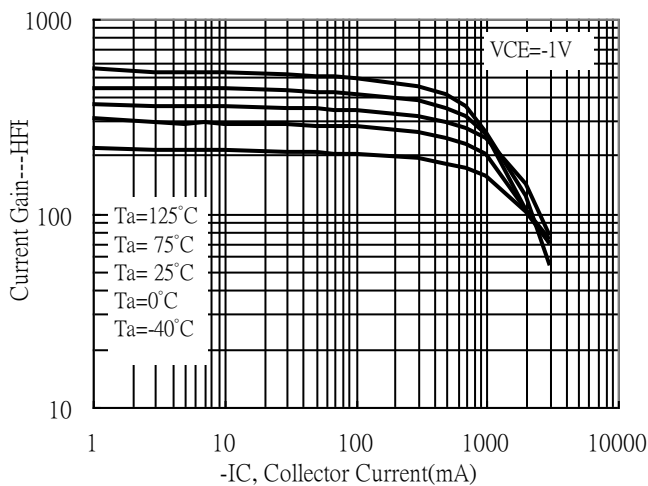
Emitter Grounded Output Characteristics



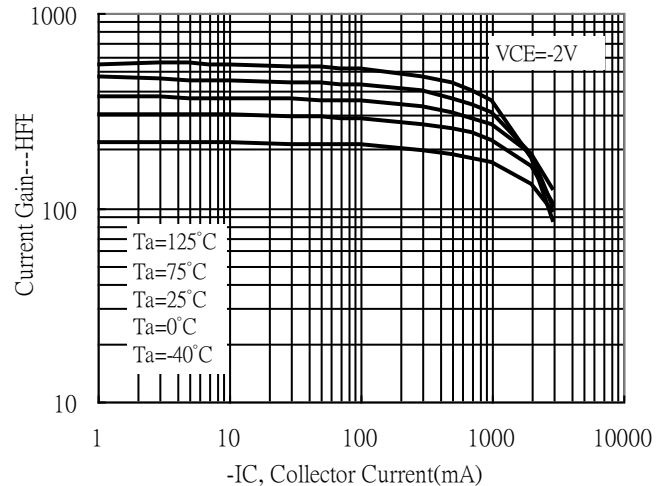
Emitter Grounded Output Characteristics



Current Gain vs Collector Current

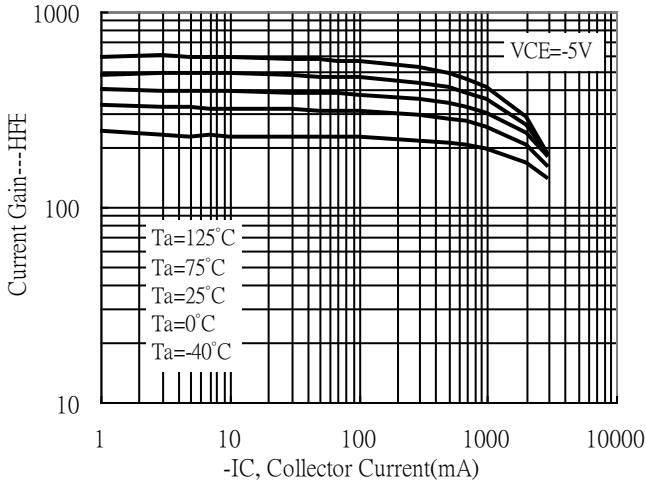


Current Gain vs Collector Current

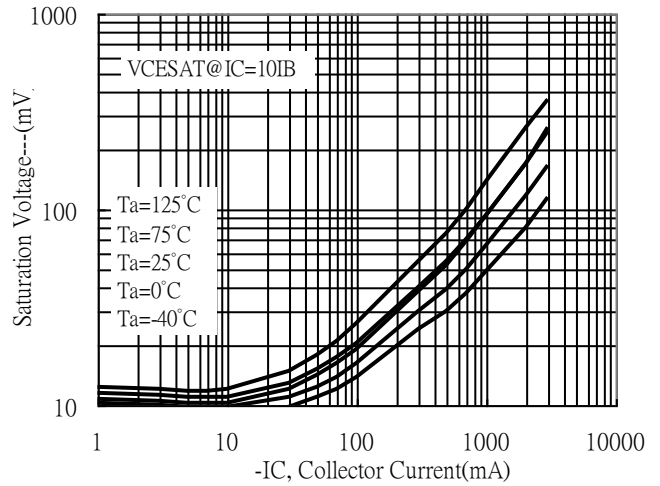


Typical Characteristics(Cont.)

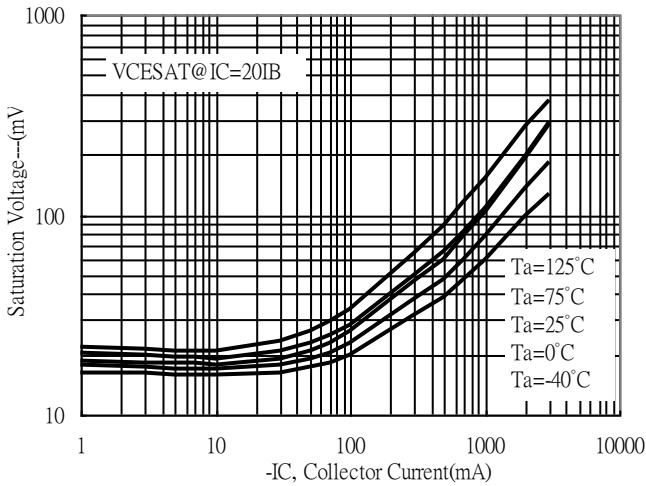
Current Gain vs Collector Current



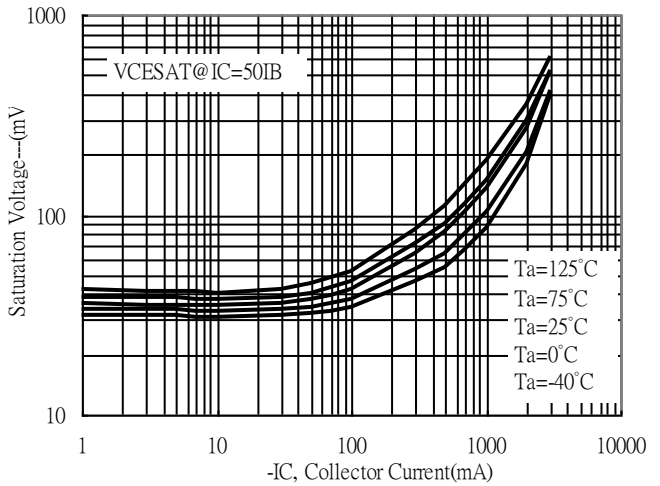
Saturation Voltage vs Collector Current



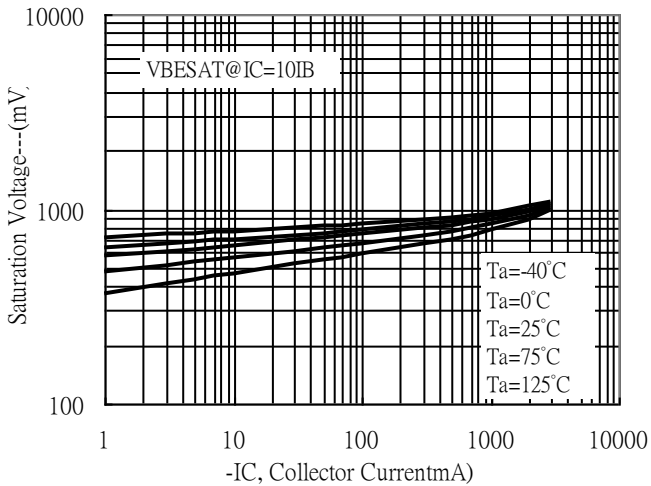
Saturation Voltage vs Collector Current



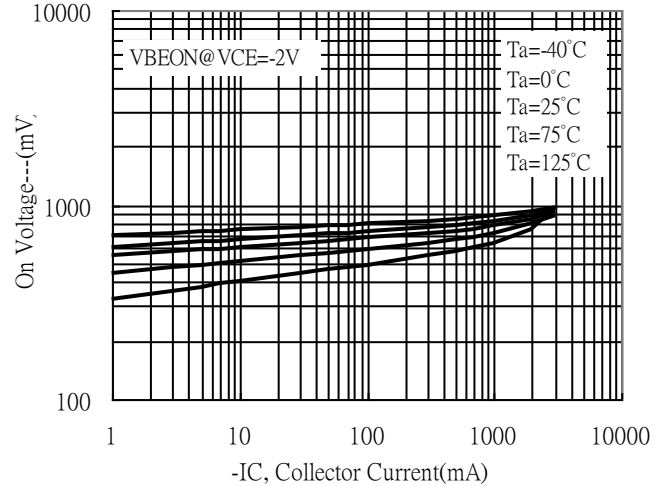
Saturation Voltage vs Collector Current



Saturation Voltage vs Collector Current



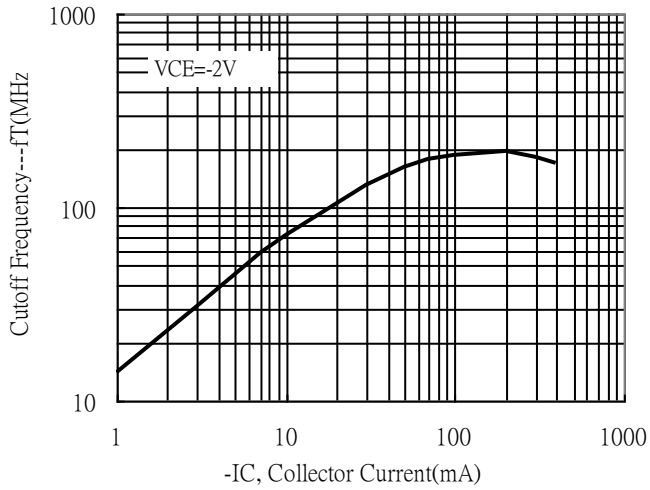
On Voltage vs Collector Current



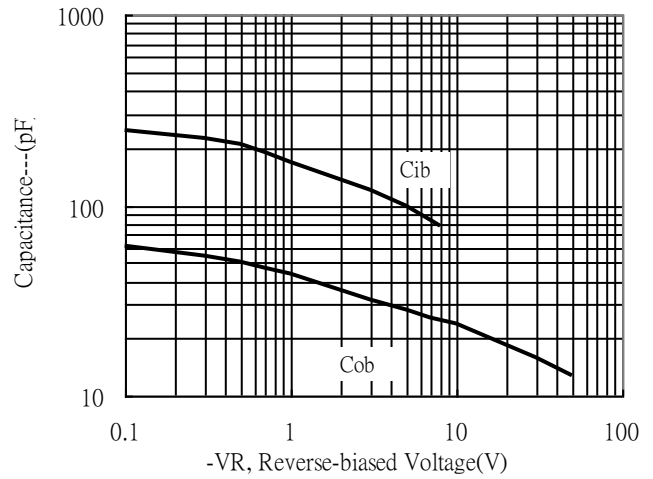


Typical Characteristics(Cont.)

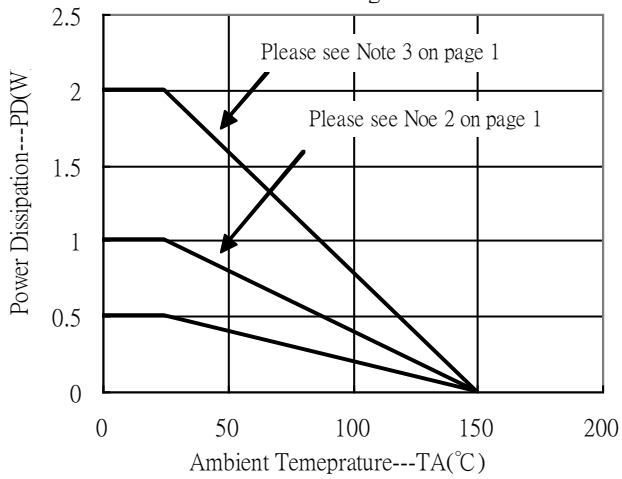
Cutoff Frequency vs Collector Current



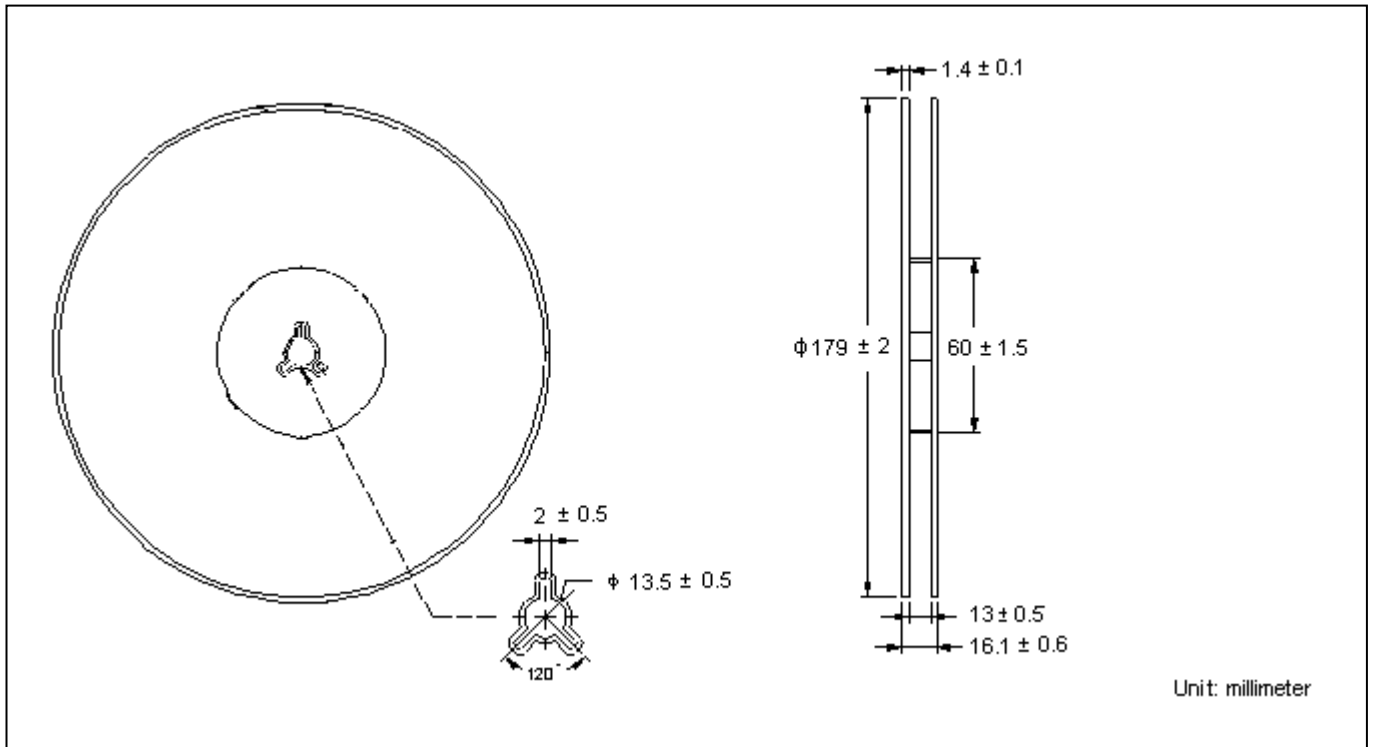
Capacitance vs Reverse-biased Voltage



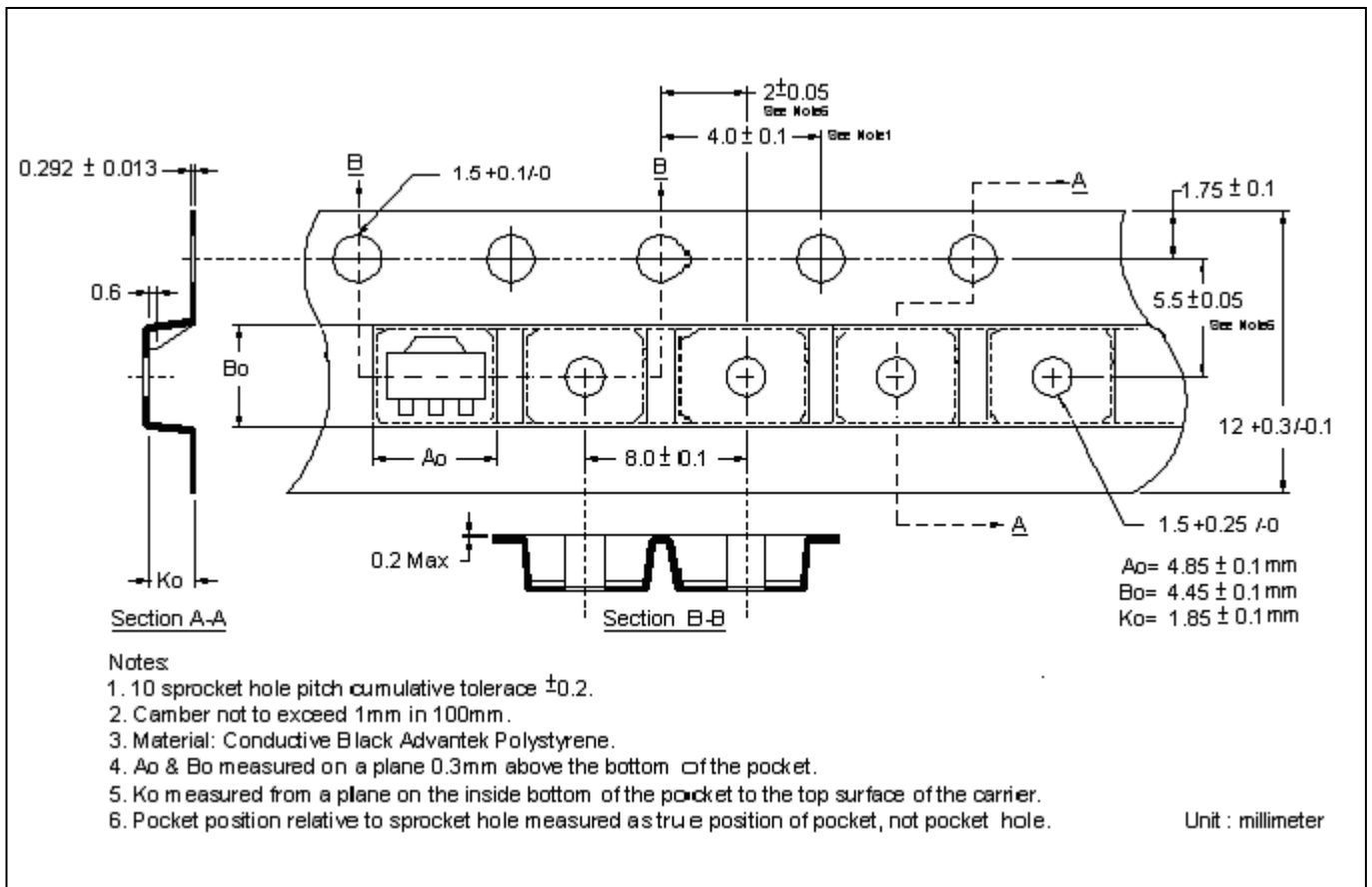
Power Derating Curves



Reel Dimension



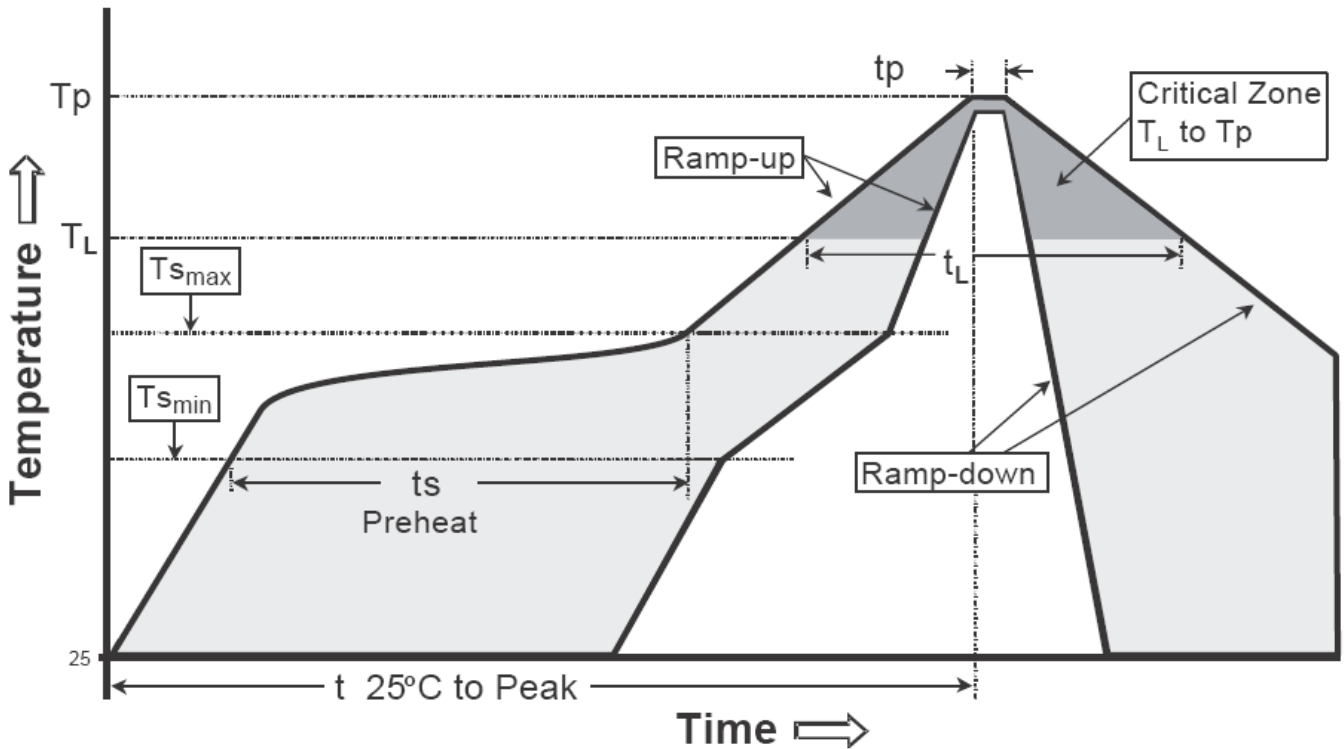
Carrier Tape Dimension



Recommended wave soldering condition

Product	Peak Temperature	Soldering Time
Pb-free devices	260 +0/-5 °C	5 +1/-1 seconds

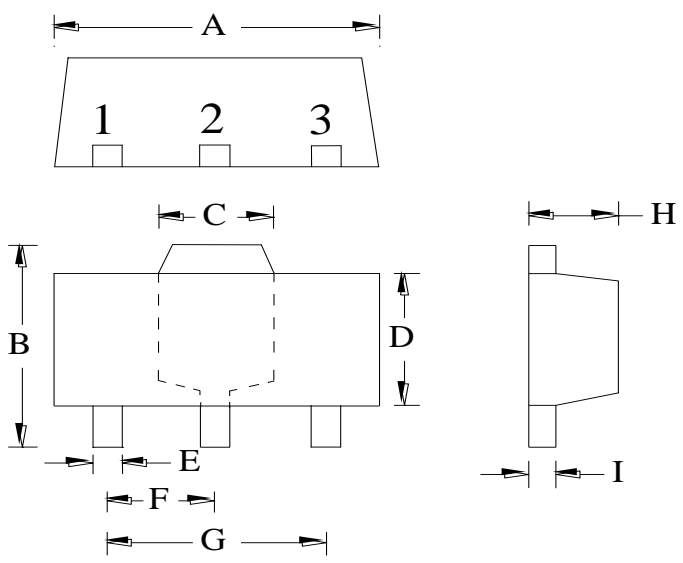
Recommended temperature profile for IR reflow



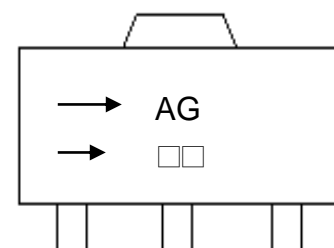
Profile feature	Sn-Pb eutectic Assembly	Pb-free Assembly
Average ramp-up rate (T _{smax} to T _p)	3°C/second max.	3°C/second max.
Preheat		
-Temperature Min(T _{s min})	100°C	150°C
-Temperature Max(T _{s max})	150°C	200°C
-Time(t _{s min} to t _{s max})	60-120 seconds	60-180 seconds
Time maintained above:		
-Temperature (T _L)	183°C	217°C
- Time (t _L)	60-150 seconds	60-150 seconds
Peak Temperature(T _p)	240 +0/-5 °C	260 +0/-5 °C
Time within 5°C of actual peak temperature(tp)	10-30 seconds	20-40 seconds
Ramp down rate	6°C/second max.	6°C/second max.
Time 25 °C to peak temperature	6 minutes max.	8 minutes max.

Note : All temperatures refer to topside of the package, measured on the package body surface.

SOT-89 Dimension



Marking:



Device Code → AG
 Date Code → □□

Style: Pin 1. Base 2. Collector 3. Emitter

3-Lead SOT-89 Plastic
 Surface Mounted Package
 CYStek Package Code: M3

*: Typical

DIM	Inches		Millimeters		DIM	Inches		Millimeters	
	Min.	Max.	Min.	Max.		Min.	Max.	Min.	Max.
A	0.1732	0.1811	4.40	4.60	F	0.0591 TYP		1.50 TYP	
B	0.1551	0.1673	3.94	4.25	G	0.1181 TYP		3.00 TYP	
C	0.0610	REF	1.55	REF	H	0.0551	0.0630	1.40	1.60
D	0.0906	0.1024	2.30	2.60	I	0.0138	0.0173	0.35	0.44
E	0.0126	0.0205	0.32	0.52					

Notes: 1. Controlling dimension: millimeters.
 2. Maximum lead thickness includes lead finish thickness, and minimum lead thickness is the minimum thickness of base material.
 3. If there is any question with packing specification or packing method, please contact your local CYStek sales office.

Material:

- Lead: Pure tin plated.
- Mold Compound: Epoxy resin family, flammability solid burning class: UL94V-0.

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